

SEMICONDUCTOR DEVICE AND METHOD TO PRODUCE THE SAME

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ABSTRACT OF THE DISCLOSURE

10 The present invention provides a semiconductor
device, using a bonding wire for linking a semiconductor
terminal to a connecting terminal for an outside circuit,
capable of preventing short circuits of the bonding wires
and excellent in strength and fatigue resistance of the
bonding joints to cope with the downsizing of the
terminals and the bonding materials, in which device the
15 bonding wires are reinforced, partially or wholly, with a
reinforcing material after bonding work and joint bulbs
bonded to the terminals using bonding material are
plated, and a method to produce the same.